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(12) **United States Design Patent**
Guenther

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(54) **ELECTRONIC SIGNATURE PAD**

(75) Inventor: **Andreas Guenther**, Stuttgart (DE)

(73) Assignee: **StepOver GmbH**, Stuttgart (DE)

(**) Term: **14 Years**

(21) Appl. No.: **29/293,029**

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May 8, 2007 (DE) 4 07 02 450

(51) **LOC (9) Cl.** **14-02**

(52) **U.S. Cl.** **D14/383**

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D14/383-387; D18/4.4, 4.6, 6, 7; 382/115,
382/116, 119, 124, 126; 346/71; 235/382,
235/382.5; 345/169, 173; 361/681-686
See application file for complete search history.

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Primary Examiner—Freda S Nunn

(74) *Attorney, Agent, or Firm*—Simpson & Simpson, PLLC

(57) **CLAIM**

The ornamental design for an electronic signature pad, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of an electronic signature pad of the present invention;

FIG. 2 is a front elevational view of the electronic signature pad;

FIG. 3 is a back elevational view of the electronic signature pad;

FIG. 4 is a top plan view of the electronic signature pad;

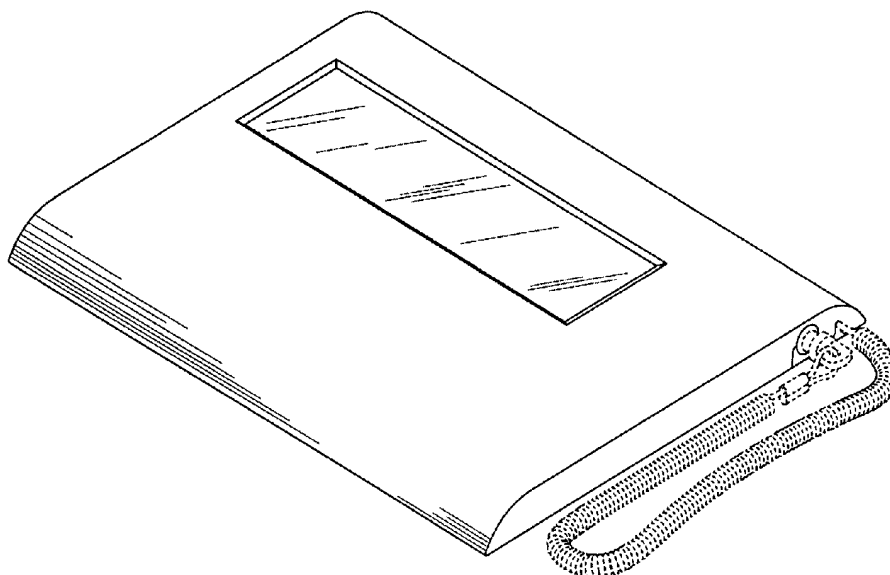
FIG. 5 is a bottom plan view of the electronic signature pad;

FIG. 6 is a right side elevational view of the electronic signature pad; and,

FIG. 7 is a left side elevational view of the electronic signature pad.

The broken lines shown are for illustrative purposes only and form no part of the claimed design.

1 Claim, 7 Drawing Sheets



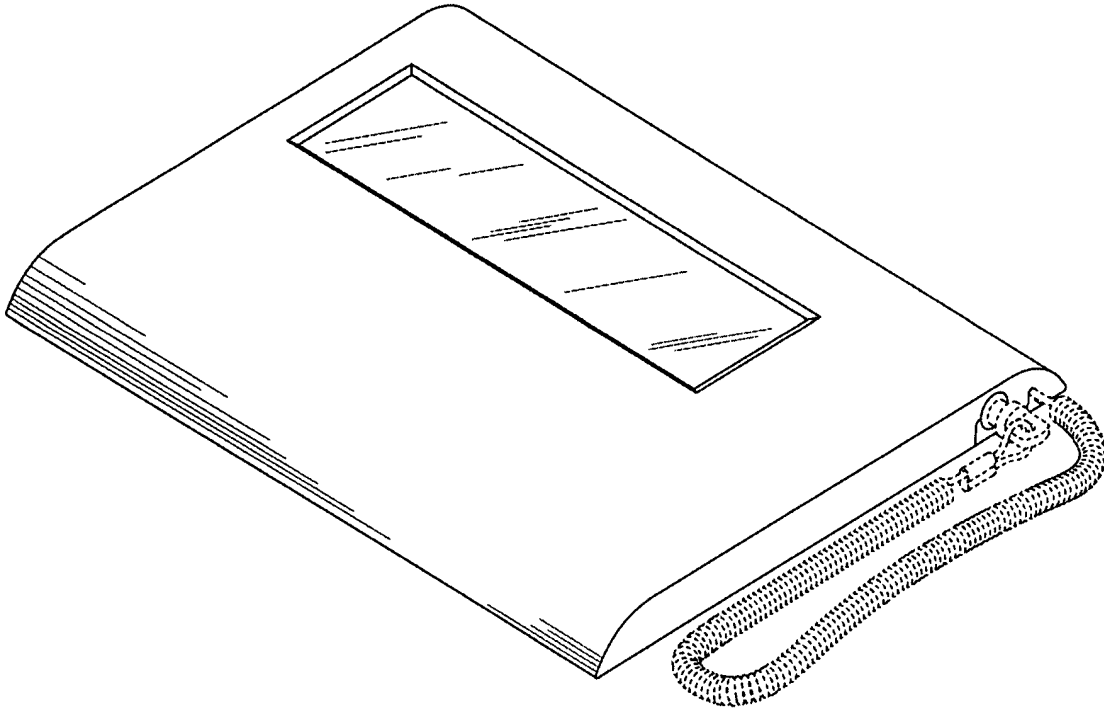


Fig. 1

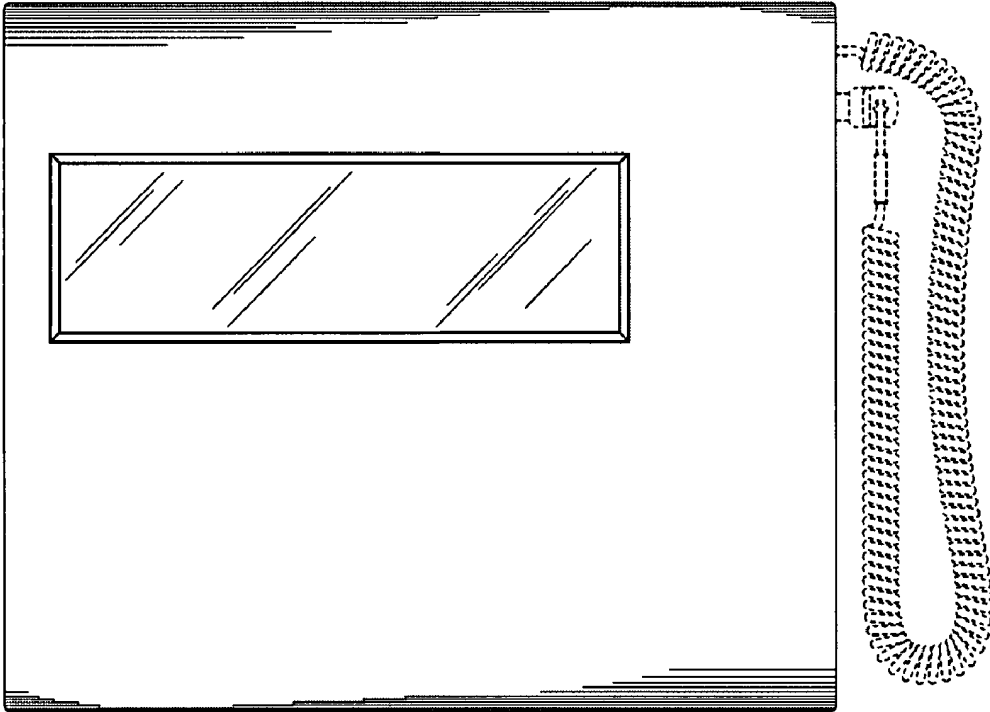


Fig. 2

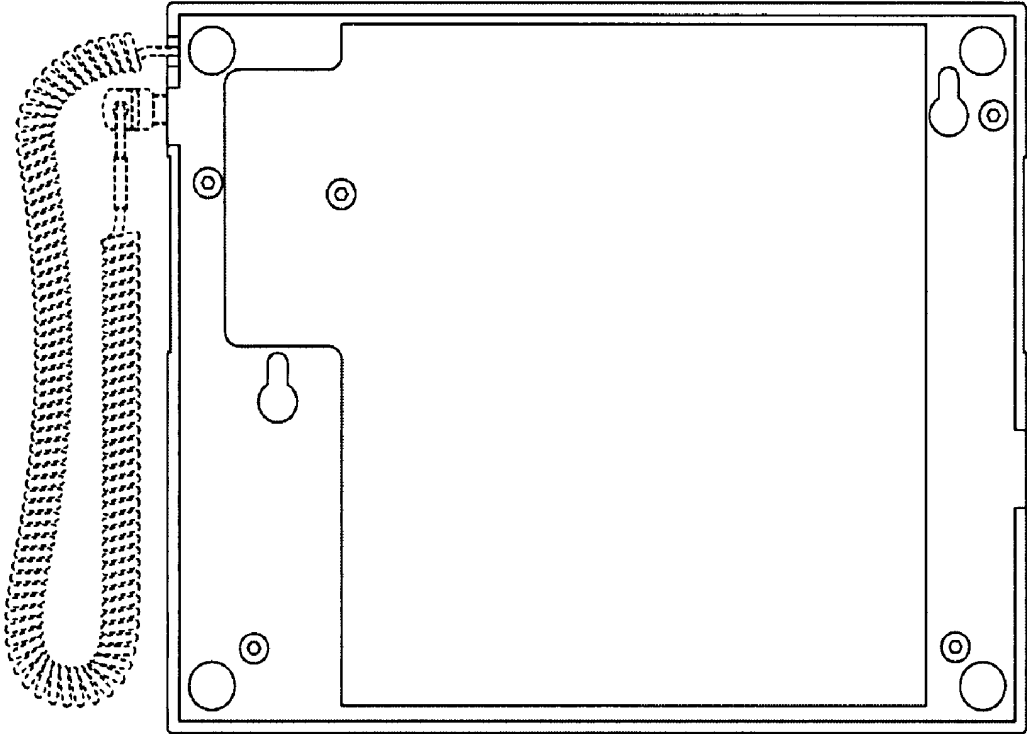


Fig. 3



Fig. 4



Fig. 5



Fig. 6



Fig. 7